



**CHENMKO ENTERPRISE CO.,LTD**

**SURFACE MOUNT**  
**N-Channel Enhancement Mode Field Effect Transistor**  
 VOLTAGE 60 Volts CURRENT 115 mAmpere

**2N7002ESEPT**

*Lead free devices*

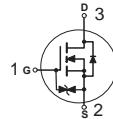
#### APPLICATION

- \* Relay driver
- \* High speed line driver
- \* Logic level transistor

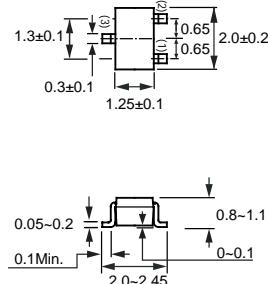
#### FEATURE

- \* Small surface mounting type. (SC-70/SOT-323)
- \* High density cell design for low R<sub>DSON</sub>.
- \* Suitable for high packing density.
- \* Rugged and reliable.
- \* High saturation current capability.
- \* ESD protect in input gate 1.5KV

#### CIRCUIT



**SC-70/SOT-323**



Dimensions in millimeters

**SC-70/SOT-323**

#### Absolute Maximum Ratings

T<sub>A</sub> = 25°C unless otherwise noted

Symbol	Parameter	2N7002ESEPT	Units
V <sub>DSS</sub>	Drain-Source Voltage	60	V
V <sub>GSS</sub>	Gate-Source Voltage	±20	V
I <sub>D</sub>	Maximum Drain Current - Continuous	115	mA
	- Pulsed (Note 1)	800	
P <sub>D</sub>	Maximum Power Dissipation (Note 2)	225	mW
T <sub>J</sub>	Operating Temperature Range	-55 to 150	°C
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	°C

Note : 1. P<sub>w</sub> <= 10uS , Duty <= 1%  
 2. When mounted on a 1"0.75"0.062 inch glass epoxy board.

2009-09

## ELECTRICAL CHARACTERISTIC ( 2N7002ESEPT )

**Electrical Characteristics**  $T_A = 25^\circ\text{C}$  unless otherwise noted

Symbol	Parameter	Conditions	Min	Typ	Max	Units
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### OFF CHARACTERISTICS

$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}} = 0 \text{ V}, I_D = 10 \mu\text{A}$	60			V
$I_{\text{DSS}}$	Zero Gate Voltage Drain Current	$V_{\text{DS}} = 60 \text{ V}, V_{\text{GS}} = 0 \text{ V}$		1		$\mu\text{A}$
		$T_J=125^\circ\text{C}$		0.5		mA
$I_{\text{GSSF}}$	Gate - Body Leakage, Forward	$V_{\text{GS}} = 20 \text{ V}, V_{\text{DS}} = 0 \text{ V}$		10		$\mu\text{A}$
$I_{\text{GSSR}}$	Gate - Body Leakage, Reverse	$V_{\text{GS}} = -20 \text{ V}, V_{\text{DS}} = 0 \text{ V}$		-10		$\mu\text{A}$

### ON CHARACTERISTICS (Note 1)

$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{DS}} = V_{\text{GS}}, I_D = 250 \mu\text{A}$	1.0	1.85	2.5	V
$R_{\text{DS(ON)}}$	Static Drain-Source On-Resistance (Note 3)	$V_{\text{GS}} = 5 \text{ V}, I_D = 50 \text{ mA}$			7.5	$\Omega$
$R_{\text{DS(ON)}}$		$V_{\text{GS}} = 10 \text{ V}, I_D = 500 \text{ mA}$			7.5	
$g_{\text{FS}}$	Forward Transconductance (Note 3)	$V_{\text{DS}} = 10 \text{ V}, I_D = 200 \text{ mA}$	80			$\text{mS}$

### DYNAMIC CHARACTERISTICS

$C_{\text{iss}}$	Input Capacitance	$V_{\text{DS}} = 25 \text{ V}, V_{\text{GS}} = 0 \text{ V}, f = 1.0 \text{ MHz}$		25	50	pF
$C_{\text{oss}}$	Output Capacitance			10	25	
$C_{\text{rss}}$	Reverse Transfer Capacitance			3.0	5	
$t_{\text{on}}$	Turn-On Time (Note 3)	$V_{\text{DD}} = 30 \text{ V}, R_L = 150 \Omega, I_D = 200 \text{ mA}, V_{\text{gen}} = 10 \text{ V}, R_{\text{GEN}} = 10 \Omega$		12	20	nS
$t_{\text{r}}$	Turn-Off Time (Note 3)			20	30	

Note:  
3. Pulse Test: Pulse Width  $\leq 300\mu\text{s}$ , Duty Cycle  $\leq 1.0\%$ .

## RATING CHARACTERISTIC CURVES (2N7002ESEPT)

### Typical Electrical Characteristics

Figure 1. Output Characteristics

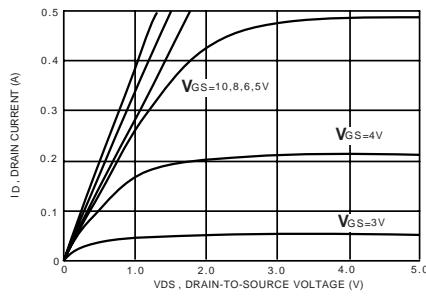


Figure 2. Transfer Characteristics

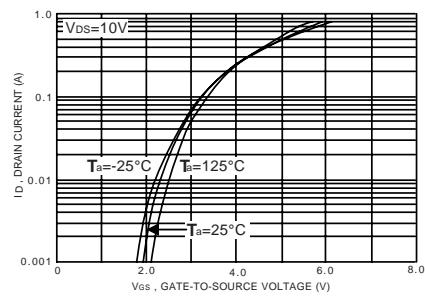


Figure 3. On-Resistance Variation with Temperature

